

SKiiP 1814 GB17E4-3DUL



SKiiP® 4

2-pack-integrated intelligent Power System

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Features

- Intelligent Power Module
- Integrated current and temperature measurement
- Integrated DC-link measurement
- Solder free power section
- IGBT4 and CAL4F technology
- $T_{jmax} = 175^{\circ}\text{C}$
- Safety isolated switching and sensor signals
- Digital signal transmission
- 100% tested IPM
- RoHS compliant
- UL recognition in progress, file no. E242581

Typical Applications*

- Renewable energies
- Traction
- Elevators
- Industrial drives

Remarks

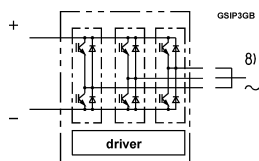
For further information please refer to SKiiP@4 Technical Explanation

Absolute Maximum Ratings

| Symbol | Conditions | Values | Unit |
|------------------|--|---------------|--------------------|
| System | | | |
| V_{CC} | Operating DC link voltage | 1300 | V |
| V_{isol} | DC, $t = 1$ s, each polarity | 5600 | V |
| $I_{t(RMS)}$ | per AC terminal, rms, sinusoidal current | 500 | A |
| $I_{max (peak)}$ | Max. peak current of power section | 2700 | A |
| f_{out} | fundamental output frequency | 1 | kHz |
| T_{stg} | storage temperature | -40 ... 85 | $^{\circ}\text{C}$ |
| IGBT | | | |
| V_{CES} | $T_j = 25^{\circ}\text{C}$ | 1700 | V |
| I_C | $T_j = 175^{\circ}\text{C}$ | 2547 | A |
| | $T_s = 25^{\circ}\text{C}$ | 2049 | A |
| | $T_s = 70^{\circ}\text{C}$ | 1800 | A |
| I_{Cnom} | | 1800 | A |
| T_j | junction temperature | -40 ... 175 | $^{\circ}\text{C}$ |
| Diode | | | |
| V_{RRM} | $T_j = 25^{\circ}\text{C}$ | 1700 | V |
| I_F | $T_j = 175^{\circ}\text{C}$ | 1771 | A |
| | $T_s = 25^{\circ}\text{C}$ | 1401 | A |
| | $T_s = 70^{\circ}\text{C}$ | 1800 | A |
| I_{Fnom} | | 1800 | A |
| T_j | junction temperature | -40 ... 175 | $^{\circ}\text{C}$ |
| Driver | | | |
| V_s | power supply | 19.2 ... 28.8 | V |
| V_{iH} | input signal voltage (high) | $V_s + 0.3$ | V |
| dv/dt | secondary to primary side | 75 | kV/ μs |
| f_{sw} | switching frequency | 15 | kHz |

Characteristics

| Symbol | Conditions | min. | typ. | max. | Unit |
|--------------------|-------------------------------|-----------------------------|------|--------|------------|
| IGBT | | | | | |
| $V_{CE(sat)}$ | $I_C = 1800$ A at terminal | $T_j = 25^{\circ}\text{C}$ | 2.12 | 2.49 | V |
| | | $T_j = 150^{\circ}\text{C}$ | 2.58 | 2.79 | V |
| V_{CE0} | | $T_j = 25^{\circ}\text{C}$ | 1.10 | 1.20 | V |
| | | $T_j = 150^{\circ}\text{C}$ | 1.00 | 1.10 | V |
| r_{CE} | at terminal | $T_j = 25^{\circ}\text{C}$ | 0.57 | 0.71 | m Ω |
| | | $T_j = 150^{\circ}\text{C}$ | 0.88 | 0.94 | m Ω |
| $E_{on} + E_{off}$ | $I_C = 1800$ A | $V_{CC} = 900$ V | 1335 | | mJ |
| | | $T_j = 150^{\circ}\text{C}$ | 2130 | | mJ |
| $R_{th(j-s)}$ | per IGBT switch | | | 0.0183 | K/W |
| $R_{th(j-r)}$ | per IGBT switch | | | 0.011 | K/W |



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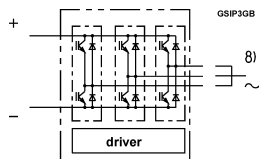
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| Characteristics | | | | | | |
|-------------------|---|-----------------------------|-------------|------------------|------------------|--------------------|
| Symbol | Conditions | | min. | typ. | max. | Unit |
| Diode | | | | | | |
| $V_F = V_{EC}$ | $I_F = 1800\text{ A}$ at terminal | $T_j = 25^{\circ}\text{C}$ | | 2.02 | 2.34 | V |
| | | $T_j = 150^{\circ}\text{C}$ | | 2.27 | 2.62 | V |
| V_{F0} | | $T_j = 25^{\circ}\text{C}$ | | 1.21 | 1.36 | V |
| | | $T_j = 150^{\circ}\text{C}$ | | 0.99 | 1.12 | V |
| r_F | at terminal | $T_j = 25^{\circ}\text{C}$ | | 0.45 | 0.55 | m Ω |
| | | $T_j = 150^{\circ}\text{C}$ | | 0.71 | 0.84 | m Ω |
| E_{rr} | $I_F = 1800\text{ A}$ $T_j = 150^{\circ}\text{C}$ | $V_R = 900\text{ V}$ | | 212 | | mJ |
| | | $V_R = 1300\text{ V}$ | | 342 | | mJ |
| $R_{th(j-s)}$ | per diode switch | | | | 0.0375 | K/W |
| $R_{th(j-r)}$ | per diode switch | | | | 0.024 | K/W |
| Driver | | | | | | |
| V_s | supply voltage non stabilized | | 19.2 | 24 | 28.8 | V |
| I_{SO} | bias current @ $V_s = 24\text{ V}$, $f_{sw} = 0$, $I_{AC} = 0$ | | | 330 | | mA |
| I_S | $k_1 = 32\text{ mA/kHz}$, $k_2 = 0.227\text{ mA/A}$ | | = 330 | $+ k_1 * f_{sw}$ | $+ k_2 * I_{AC}$ | mA |
| V_{IT+} | input threshold voltage (HIGH) | | $0,7 * V_s$ | | | V |
| V_{IT-} | Input threshold voltage (LOW) | | $0,3 * V_s$ | | | V |
| R_{IN} | input resistance | | | 13 | | k Ω |
| C_{IN} | input capacitance | | | 1 | | nF |
| t_{pRESET} | error memory reset time | | 1.3 | | 2.9 | s |
| $t_{pReset(OCP)}$ | Over current reset time | | | | | μs |
| t_{TD} | top / bottom switch interlock time | | | 3 | | μs |
| t_{jitter} | jitter clock time | | | 52 | 58 | ns |
| t_{SIS} | short pulse suppression time | | | 0.6 | | μs |
| t_{POR} | Power-On-Reset completed | | | 3.5 | | s |
| V_{CEstat} | Collector-Emitter Threshold Static Monitoring Voltage | | | 7.5 | | V |
| t_{bl} | Collector-Emitter Threshold Static Monitoring Blanking Time | | | 6 | | μs |
| $I_{digiout}$ | digital output sink current (HALT-signal) | | | | 16 | mA |
| $V_{it+ HALT}$ | input threshold voltage HIGH HALT (Low -->High) | | $0,6 * V_s$ | | | V |
| $V_{it-HALT}$ | input threshold voltage LOW HALT (High --> Low) | | | | $0,4 * V_s$ | V |
| $t_{d(Err)}$ | Error delay time (from detection to HALT), (depends on kind of error) | | 1.8 | | 170 | μs |
| I_{TRIPSC} | over current trip level | | 2645 | 2700 | 2755 | A _{PEAK} |
| T_{trip} | over temperature trip level | | 126 | 130 | 134 | $^{\circ}\text{C}$ |
| $T_{DriverTrip}$ | over temperature PCB trip level | | 113 | 120 | 124 | $^{\circ}\text{C}$ |
| V_{DCtrip} | over voltage trip level, | | 1300 | 1340 | 1380 | V |
| f_{0Uana} | bandwidth of DC-voltage measurement @ V_{DCtrip} (-3dB) | | | 2 | | kHz |
| f_{0Iana} | bandwidth of current measurement @ I_{TRIPSC} (-3dB), | | | 50 | | kHz |
| f_{0Tana} | bandwidth of temperature measurement @ T_{trip} (-3dB) | | | 5 | | Hz |



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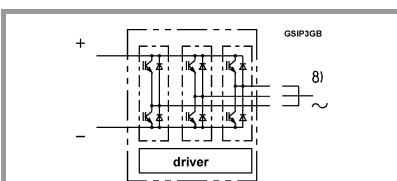
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|--------------------|--|---------------------------------|------|-------|-------|-------------------------|
| Symbol | Conditions | | min. | typ. | max. | Unit |
| System | | | | | | |
| $t_{d(on)IO}$ | $V_{CC} = 1300\text{ V}$ $I_C = 1800\text{ A}$ $T_j = 25^{\circ}\text{C}$ | turn on propagation delay time | | 2.8 | | μs |
| $t_{d(off)IO}$ | | turn off propagation delay time | | 2.6 | | μs |
| dV_{CE}/dt_{on} | $T_j = 25^{\circ}\text{C}$ $V_{CC} = 1300\text{ V}$ | $I_C = 0\text{ A}$ | | 9 | | $\text{kV}/\mu\text{s}$ |
| | | $I_C = 1800\text{ A}$ | | 2 | | $\text{kV}/\mu\text{s}$ |
| dV_{CE}/dt_{off} | | $I_C = 1800\text{ A}$ | | 9 | | $\text{kV}/\mu\text{s}$ |
| $R_{th(s-a)}$ | flow rate = $610\text{ m}^3/\text{h}$, $T_a=25^{\circ}\text{C}$, 500m above sea level | | | | 0.026 | K/W |
| R_{CC+EE} | terminals to chip, $T_s = 25^{\circ}\text{C}$ | | | 0.09 | | $\text{m}\Omega$ |
| L_{CE} | commutation inductance | | | 6 | | nH |
| C_{CHC} | coupling capacitance secondary to heat sink | | | 4.8 | | nF |
| C_{ps} | coupling capacitance primary to secondary | | | 0.067 | | nF |
| $I_{CES} + I_{RD}$ | $V_{GE} = 0\text{ V}$, $V_{CE} = 1700\text{ V}$, $T_j = 25^{\circ}\text{C}$ | | | 0.211 | | mA |
| M_{dc} | DC terminals | | 6 | | 8 | Nm |
| M_{ac} | AC terminals | | 13 | | 15 | Nm |
| w | SKiiP System w/o heat sink | | | 2.48 | | kg |
| W_h | heat sink | | | 5.9 | | kg |



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| Isolation coordination acc. to EN 50178 and IEC 61800-5-1 | |
|---|---------------------------------------|
| Maximum grid RMS voltage, line-to-line, grounded delta mains | 690V+20% |
| Installation altitude for maximum grid RMS voltage, line-to-line, grounded delta mains | 2000m |
| Maximum grid RMS voltage, line-to-line, star point grounded mains | 690V+20% |
| Installation altitude for maximum grid RMS voltage, line-to-line, star point grounded mains | 4000m |
| Maximum transient peak voltage between low voltage circuit and mains | 1900V |
| Pollution degree acc. to IEC 60664-1 outside the moulded power section | 2 |
| Overvoltage cat. acc. to IEC 60664-1 for mains | III |
| Overvoltage cat. acc. to UL 840 within mains | I |
| Overvoltage cat. acc. to UL 840 between mains and ground | III |
| Overvoltage cat. acc. to UL 840 between mains and low voltage circuit | III |
| Basic isolation | between heat sink and mains |
| Reinforced isolation | between low voltage circuit and mains |
| Protection level acc. to IEC 60529 | IP00 |

Environmental conditions acc. to IEC 60721

| | Storage | Transportation | Operation - stationary use at weatherprotected locations | Operation - ground vehicle installations | Operation - ship environment |
|---|---------|----------------|--|--|------------------------------|
| Climatic conditions | 1K2 | 2K2 | 3K3 ₍₁₎ | 5K1 | 6K1 |
| Biological conditions | 1B1 | 2B1 | 3B1 | 5B1 | 6B1 |
| Chemically active substances (excluded: salt spray) | 1C2 | 2C1 | 3C2 | 5C2 | 6C2 |
| Mechanically active substances | 1S1 | 2S1 | 3S1 | 5S1 | 6S1 |
| Mechanical conditions | 1M3 | (4) | 3M6 ₍₂₎ | 5M3 ₍₃₎ | 6M3 |
| Contaminating fluids | --- | --- | --- | 5F1 | --- |

(1) 3K3: expanded temperature range: -40°C / +85°C

(2) 3M7 possible, but due to mechanic load capacity of external components like DC-Link capacitors limited to 3M6

(3) 5M3, shock only 5M2, without impact from foreign bodies, stones

(4) no declaration due to customer-specific packing

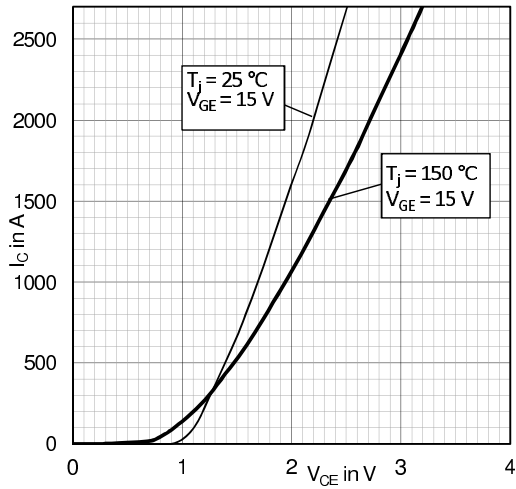


Fig. 1: Typical IGBT output characteristics

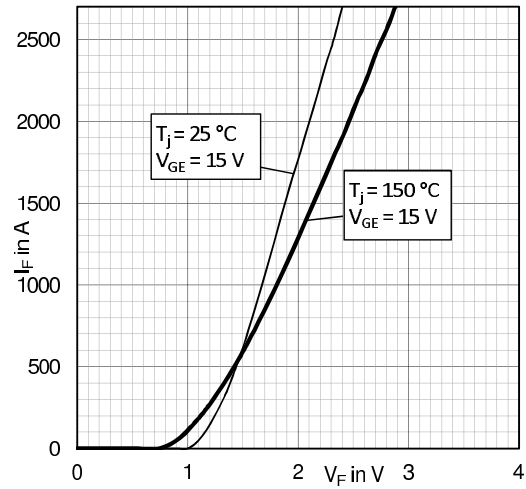


Fig. 2: Typical diode output characteristics

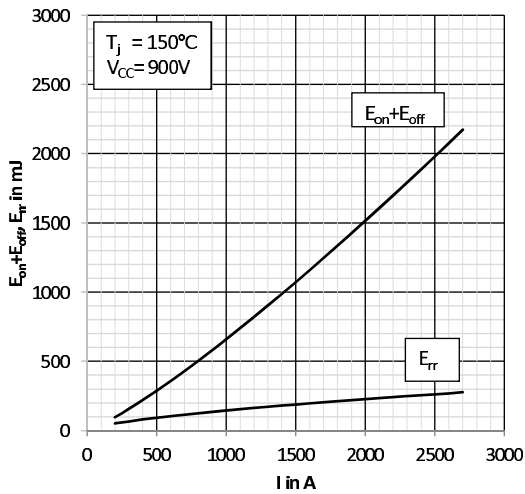


Fig. 3: Typical energy losses $E = f(I_C, V_{CC}, T_j)$

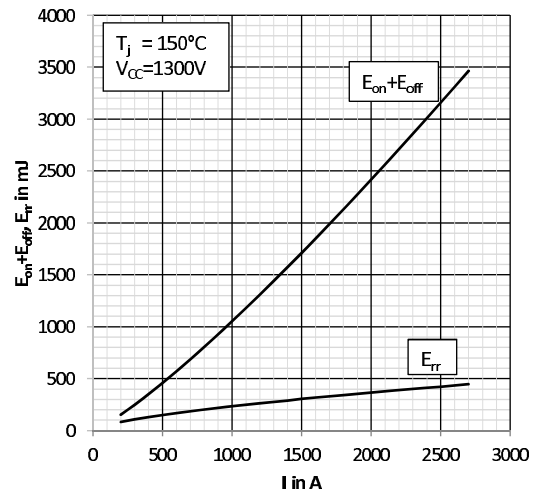


Fig. 4: Typical energy losses $E = f(I_C, V_{CC}, T_j)$

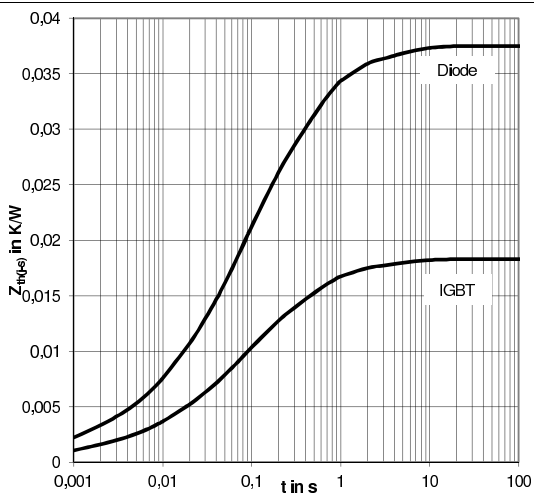


Fig. 5: Transient thermal impedance $Z_{th}(j-s)$

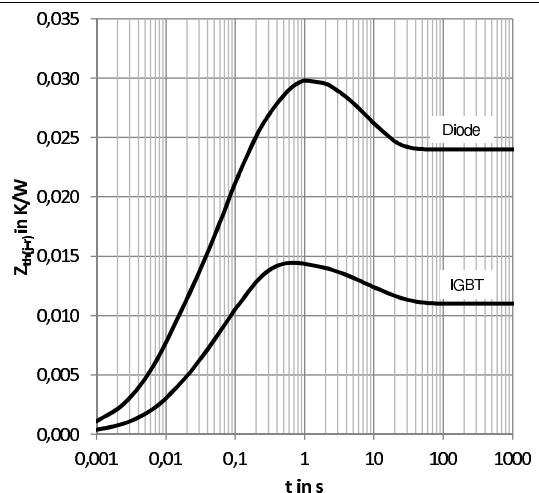


Fig. 6: Transient thermal impedance $Z_{th}(j-r)$

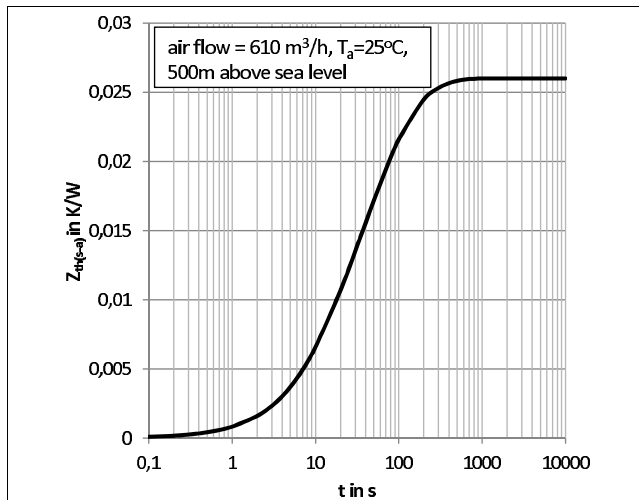


Fig. 7: Transient thermal impedance $Z_{th}(s-a)$

| | $R_{th} [K/W]$ | | | | |
|----------------|----------------|--------|--------|---------|---------|
| | 1 | 2 | 3 | 4 | 5 |
| $Z_{th}(fs) I$ | 0,0013 | 0,0065 | 0,0073 | 0,0022 | 0,0010 |
| $Z_{th}(fs) D$ | 0,0026 | 0,0134 | 0,0149 | 0,0045 | 0,0021 |
| $Z_{th}(fr) I$ | 0,0030 | 0,0042 | 0,0076 | -0,0016 | -0,0022 |
| $Z_{th}(fr) D$ | 0,0077 | 0,0135 | 0,0098 | -0,0070 | |
| $Z_{th}(s-a)$ | 0,0069 | 0,0147 | 0,0044 | | |

| | $\tau [s]$ | | | | |
|----------------|------------|--------|---------|--------|--------|
| | 1 | 2 | 3 | 4 | 5 |
| $Z_{th}(fs) I$ | 3,6500 | 0,4100 | 0,0650 | 0,0090 | 0,0008 |
| $Z_{th}(fs) D$ | 3,6500 | 0,4100 | 0,0650 | 0,0090 | 0,0008 |
| $Z_{th}(fr) I$ | 0,0120 | 0,0470 | 0,1400 | 4,9000 | 16,000 |
| $Z_{th}(fr) D$ | 0,0084 | 0,0600 | 0,3200 | 8,6000 | |
| $Z_{th}(s-a)$ | 13,2000 | 51,000 | 157,000 | | |

Fig. 8: Coefficients of thermal impedances

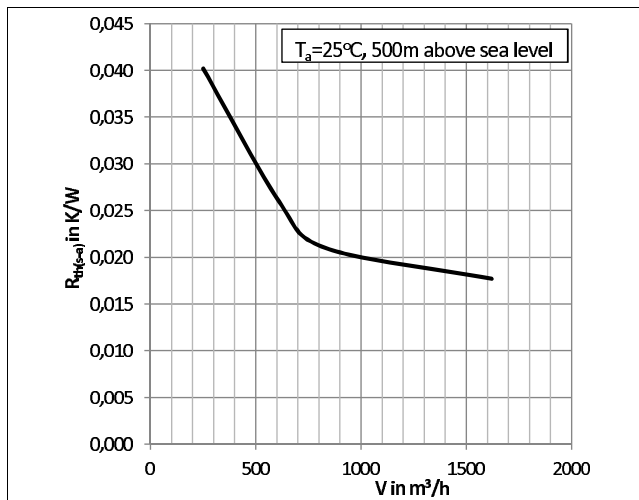


Fig. 9: Thermal resistance $R_{th}(s-a)$ versus flow rate V

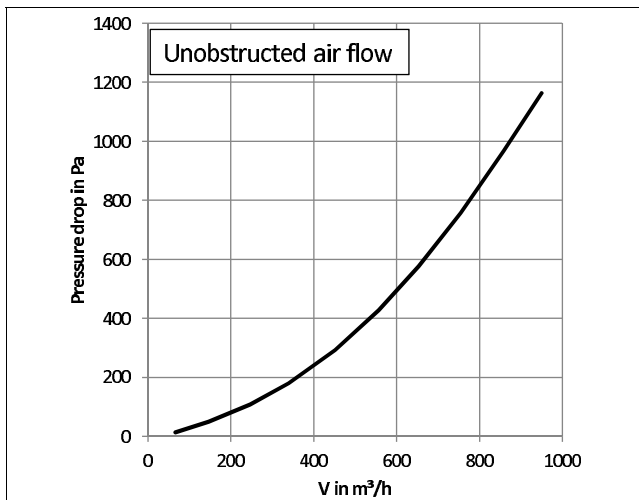
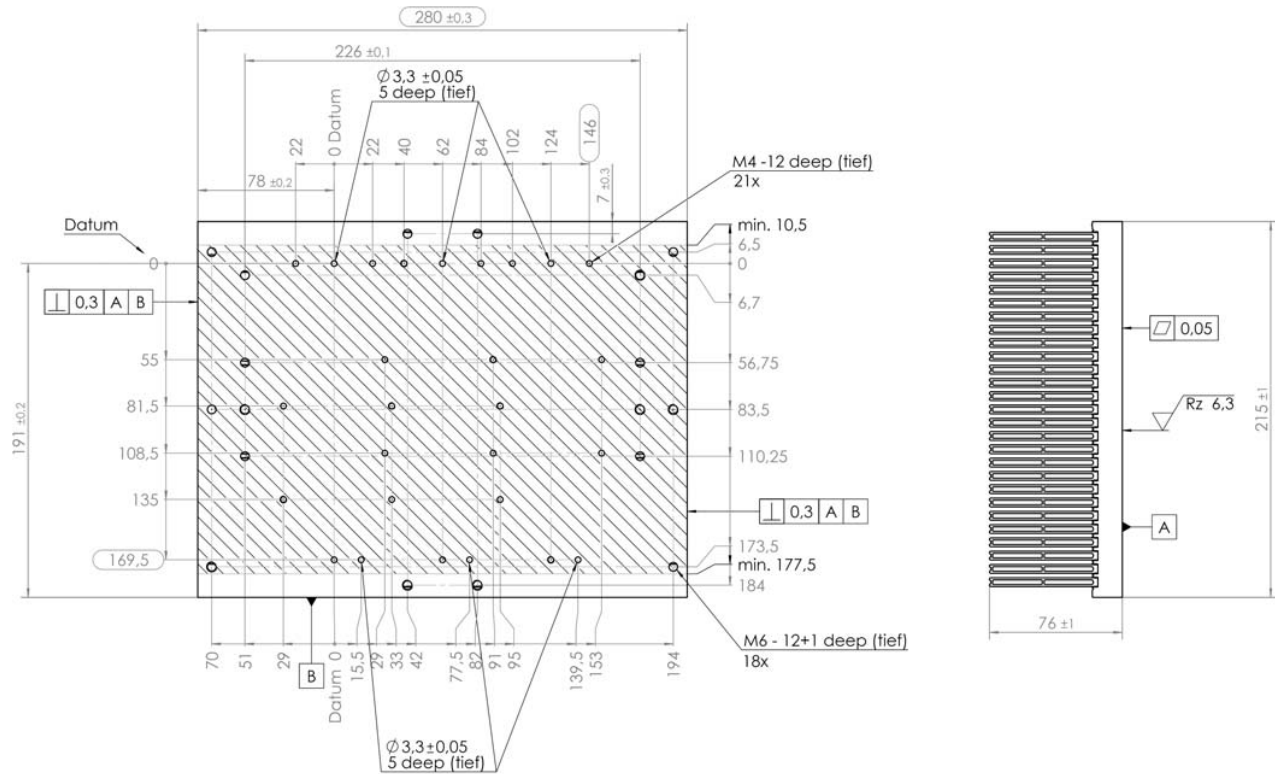


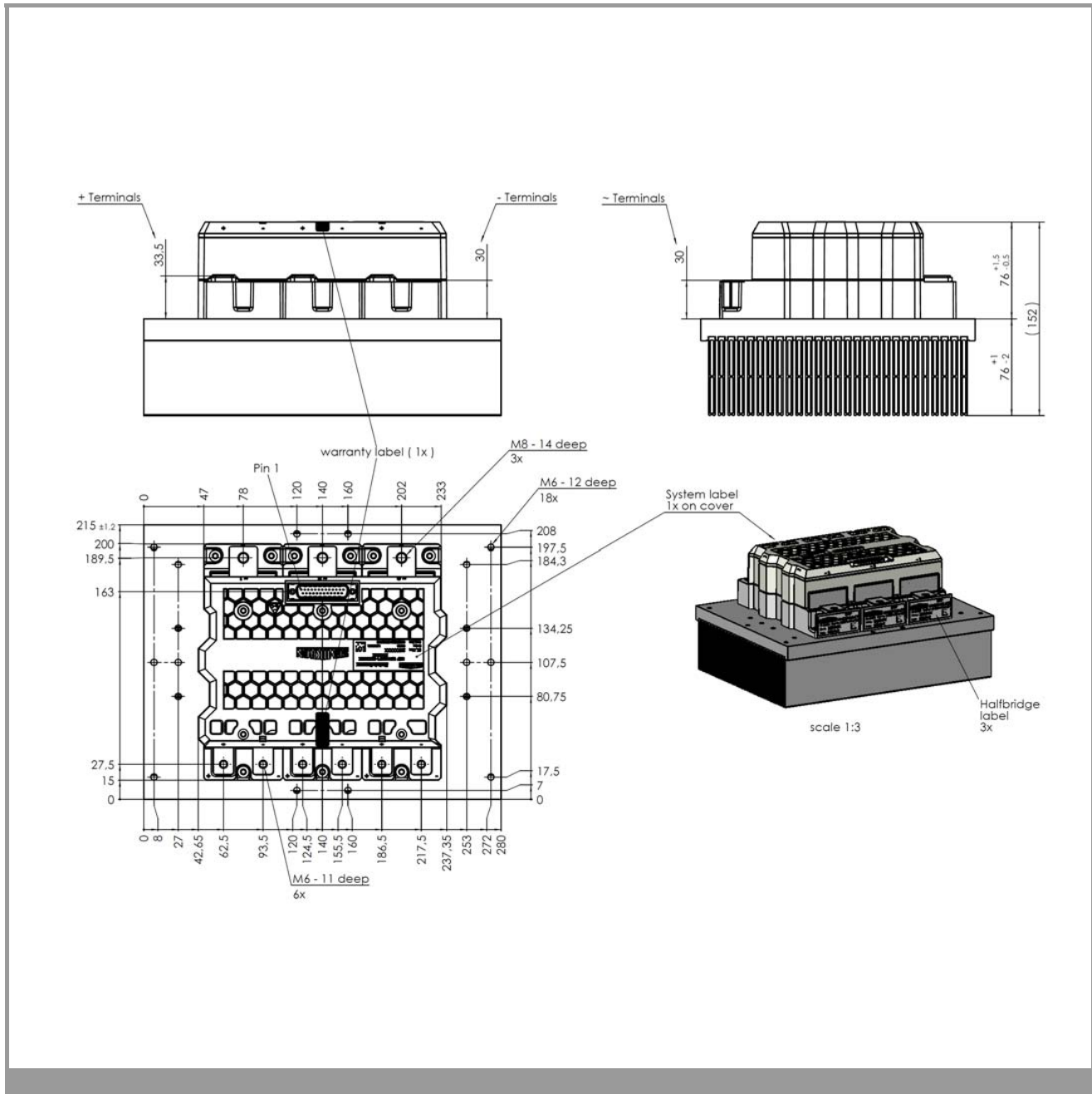
Fig. 10: Pressure drop Δp versus flow rate V

SKiIP 1814 GB17E4-3DUL



Heat sink

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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.